# General specification for 2.5mm phono jacks

**1) Rating:** DC 30V 0.3A

**2) Electrical Performance:**

| | Test Conditions | Performance |
|---|---|---|
| Contact Resistance | Measured at small current (1-mA 1000Hz or less) | 50mΩ Max. |
| Insulation Resistance | Apply a voltage of 500V DC shall be applied for 1 minute after which the following measurements are made:<br>1) Between the terminals not to be contact<br>2) Between body and terminal<br>3) Between terminals not to be contact when plug is inserted | More than 100M Ω |
| Dielectric Strength | AC 500V rms (50-60Hz) for 1 minute trip current: 0.5mA<br>1) Between terminals not to be contact.<br>2) Between body and terminals<br>3) Between terminals not to be contact when plug is inserted. | Without damage to parts arcing or breakdown. |

**3) Mechanical Performance:**

| | Test Conditions | Performance |
|---|---|---|
| Insertion Force | Measurement shall be made after 3 times of insertion and extraction with gauge plug. | 700 ~ 1400gf |
| Extraction Force | Measurement shall be made after 3 times of insertion and extraction with gauge plug. | 500 ~ 1000gf |
| Terminal Strength | A static load of 300gf shall be applied to the terminals for 15 seconds in any direction. | Electrical characteristics shall be satisfied without damage or excessive looseness of terminals. |
| Life Test | Endurance without loading:<br>Connector shall be subjected to 5,000 cycles at a rate of 15 to 18 cycles per minutes without load. | 1) Contact resistance: 100mΩ Max.<br>2) Insulation resistance: 50MΩ Min.<br>3) Withstand Voltage: AC 500V 1 minute<br>4) Without damage to parts arcing or breakdown. |

# General specification for 2.5mm phono jacks

**4) Environmental:**

| | Test Conditions | Performance |
|---|---|---|
| Solder ability Test | The top of terminals shall be dipped 2mm in the solder bath of 245±5°C for 3±0.5 seconds. | The area of soldering should be over 75% |
| Resistance to Soldering Heat Test | Solder Bath Method:<br>Solder temperature 255±5°C immersion time within 5 seconds. Immersion depth up to the surface of the board 1.6mm dimensions of component holes in the printed wiring board shall be in accordance with those specified in this specification.<br><br>Solder Iron Method:<br>Temperature of solder 350±10°C time of solder 3±0.5 seconds. | Without deformation of body or excessive looseness of terminals electrical characteristics shall be satisfied. |
| Cold Test | The connector shall be stored at a temperature of -25±3°C for 48 hours, then the connector shall be maintained at standard atmospheric conditions for 1 hour after which measurements shall be made | There shall be no deformation or cracks in molded parts. |
| Heat Test | The connector shall be stored at a temperature of 70±2°C for 48 hours, then the switch shall be maintained at standard atmospheric conditions for 1 hour after which measurements shall be made.. | There shall be no deformation or cracks to the molded part. |
| Humidity Test | The connector shall be stored at a temperature of 40±2°C and a humidity of 90% to 98% for 48 hours, then the connector shall be maintained at standard atmospheric conditions for 1 hour after which measurements shall be made. | There shall be no deformation or cracks to the molded part. |

**5)** Test Condition ( unless otherwise specified):
Temperature : 5°C – 35°C
Humidity : 45% - 85% R.H.
Pressure: 86 106kPa

**6)** Construction: Shape and dimensions subject to attached chart regulation.